Injoon Son

List of Publications by Year in descending order

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1040056 1199594 39 175 9 12 citations h-index g-index papers 39 39 39 150 docs citations times ranked citing authors all docs

INIOON SON

#	Article	IF	CITATIONS
1	Thermomechanical stability of Bi2Te3-based thermoelectric modules employing variant diffusion barriers. Intermetallics, 2022, 140, 107404.	3.9	7
2	Performance of Bi2Te3-based thermoelectric modules tailored by diffusion barriers. Journal of Alloys and Compounds, 2022, 895, 162716.	5.5	12
3	Effect of Solution Temperature on Electrodeposition Behavior of Zn-Ni Alloy from Alkaline Zincate Solution. Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan, 2022, 108, 120-130.	0.4	6
4	Synergistic Effect of Brightener and Solution Temperature on the Electrodeposition Behavior of Zn-Ni Alloy from Alkaline Zincate Solution. Tetsu-To-Hagane/Journal of the Iron and Steel Institute of Japan, 2022, 108, 268-281.	0.4	4
5	Novel silver-enhanced hard gold electrodeposit applied for electrical contacts: comparison with conventional gold–cobalt alloy. Transactions of the Institute of Metal Finishing, 2022, 100, 213-220.	1.3	1
6	Synergistic Effect of Brightener and Solution Temperature on the Electrodeposition Behavior of Zn–Ni Alloy from Alkaline Zincate Solution. ISIJ International, 2022, , .	1.4	5
7	Fabrication and mechanical properties of Al–Si-based alloys by selective laser melting process. Powder Metallurgy, 2021, 64, 198-205.	1.7	3
8	Enhancement of bonding strength in BiTe-based thermoelectric modules by electroless nickel, electroless palladium, and immersion gold surface modification. Applied Surface Science, 2021, 545, 149005.	6.1	14
9	Thermal Stability of Electroless NiP Diffusion Barrier on BiTe-Based Thermoelectric Materials. Journal of Nanoelectronics and Optoelectronics, 2021, 16, 812-818.	0.5	1
10	Improved contact resistance and solderability of electrodeposited Au-Sn alloy layer with high thermal stability for electronic contacts. Applied Surface Science, 2021, 551, 149405.	6.1	4
11	Effect of Reaction Product of Epichlorohydrin and Imidazole on the Electrodeposition Behavior of Zn–Ni Alloy from Alkaline Zincate Solution. ISIJ International, 2021, 61, 2256-2263.	1.4	12
12	Effect of Plating Layers on the Bonding Strength of p-Type Bi–Te Thermoelectric Elements. Journal of Nanoscience and Nanotechnology, 2021, 21, 4503-4507.	0.9	0
13	Effect of the Electroless Nickel, Electroless Palladium, and Immersion Gold Multilayer as a Diffusion Barrier on the Bonding Strength of BiTe-Based Thermoelectric Modules. Journal of Nanoscience and Nanotechnology, 2021, 21, 4498-4502.	0.9	1
14	Enhanced output power of thermoelectric modules with reduced contact resistance by adopting the optimized Ni diffusion barrier layer. Journal of Alloys and Compounds, 2021, 884, 161119.	5.5	9
15	Smelting of Platinum Group Metals and Recycling of Spent Catalyst. , 2021, 30, 18-29.		3
16	Removal of Fe from Metallurgical Grade Si by Directional Solidification. , 2021, 30, 20-26.		1
17	Characterization of Copper–Graphite Composites Fabricated via Electrochemical Deposition and Spark Plasma Sintering. Applied Sciences (Switzerland), 2019, 9, 2853.	2.5	9
18	Acid Palladium-Nickel Electroplating Using Ethylenediamine as Complexing Agent. Journal of Nanoscience and Nanotechnology, 2019, 19, 4276-4281.	0.9	0

Injoon Son

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19	Effect of Etching Time and Temperature on Plating Adhesion of Acrylonitrile Butadiene Styrene (ABS)-Based Material. Journal of Nanoscience and Nanotechnology, 2019, 19, 4282-4286.	0.9	2
20	Effects of the Process Conditions on the Color of Dye-Treated Anodized AA5052. Journal of Nanoscience and Nanotechnology, 2019, 19, 4097-4102.	0.9	0
21	Effect of Surface Roughness and Electroless Ni–P Plating on the Bonding Strength of Bi–Te-based Thermoelectric Modules. Coatings, 2019, 9, 213.	2.6	9
22	Fabrication of a Bi ₂ Te ₃ -Based Thermoelectric Module Using Tin Electroplating and Thermocompression Bonding. Journal of Nanoscience and Nanotechnology, 2019, 19, 1738-1742.	0.9	0
23	Wet Etching Method for Electroless Ni–P Plating of Bi–Te Thermoelectric Element. Journal of Nanoscience and Nanotechnology, 2019, 19, 1749-1754.	0.9	1
24	Fabrication of an Aluminum-Based Thermoelectric Module Substrate via Anodization and Nickel Plating. Journal of Nanoscience and Nanotechnology, 2019, 19, 1474-1479.	0.9	0
25	Self-Propagating Heat Synthetic Reactivity of Fine Aluminum Particles via Spontaneously Coated Nickel Layer. Scientific Reports, 2019, 9, 1033.	3.3	12
26	Effects of Hexamethylenetetramine Concentration on the Structure and Capacitance Characteristics of Ni(OH)2 Pseudocapacitors Produced By Electrodeposition ECS Meeting Abstracts, 2019, , .	0.0	0
27	Fabrication of Aluminum-Based Thermal Radiation Plate for Thermoelectric Module Using Aluminum Anodic Oxidization and Copper Electroplating. Journal of Nanoscience and Nanotechnology, 2018, 18, 6404-6409.	0.9	2
28	A Novel Fabrication Method of Bi ₂ Te ₃ -Based Thermoelectric Modules by Indium Electroplating and Thermocompression Bonding. Journal of Nanoscience and Nanotechnology, 2018, 18, 6515-6519.	0.9	2
29	Wet Etching Method for the Electroless Ni–P Plating of Bi2-Te3 Thermoelectric Elements. ECS Meeting Abstracts, 2018, , .	0.0	0
30	The influence of interfacial defect-region on the thermoelectric properties of nanodiamond-dispersed Bi 2 Te 2.7 Se 0.3 matrix composites. Applied Surface Science, 2017, 415, 109-113.	6.1	14
31	Influence of Electroless Ni-P and Pd-P Plating on the Bonding Strength of n-Type Bi-Te Thermoelements. Journal of Nanoscience and Nanotechnology, 2017, 17, 7603-7608.	0.9	3
32	The Influence of Surface Functionalization on the Thermoelectric Properties of Carbon Nanotube/Bi ₂ Te ₃ Composites. Journal of Nanoscience and Nanotechnology, 2016, 16, 10777-10781.	0.9	3
33	Effect of Equal Channel Angular Pressing on the Pitting Corrosion Resistance of Hard Anodized Al5052 Alloy. Journal of the Korean Institute of Surface Engineering, 2015, 48, 142-148.	0.1	2
34	Palladium-Nickel Alloy Electrodeposition Using Ethylenediamine as Complexing Agent. Journal of the Korean Institute of Surface Engineering, 2014, 47, 215-220.	0.1	1
35	Effect of pH on the morphological evolution of NiO thin film synthesized on ZnO nanorod arrays by electrodeposition and post-annealing. Materials Letters, 2013, 101, 65-68.	2.6	10
36	Synthesis and Thermoelectric Properties of Carbon Nanotube-Dispersed Bi ₂ Te ₃ Matrix Composite Powders by Chemical Routes. Journal of Korean Powder Metallurgy Institute, 2013, 20, 345-349.	0.3	6

Injoon Son

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37	Effect of Alloying Elements and Thermal Aging on the Contact Resistance of Electroplated Gold Alloy Layers. Journal of the Korean Institute of Surface Engineering, 2013, 46, 235-241.	0.1	0
38	Effect of Equal-Channel Angular Pressing on Pitting Corrosion of Pure Aluminum. International Journal of Corrosion, 2012, 2012, 1-9.	1.1	15
39	Effect of Electroless Ni-P Plating on the Bonding Strength of PbTe Thermoelectric Module Using Silver Alloy-Based Brazing. Materials Science Forum, 0, 985, 16-22.	0.3	1